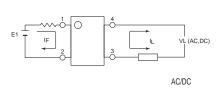
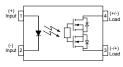
SUPSIC®

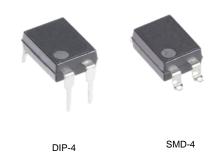
Parameter	Symbol	Rating	Units	
Load Voltage	VL	400	V	
Load Current	lL l	0.35	Α	
On-Resistance	Ron	8	Ω	
I/O Isolation Voltage	V/io	5000	Vrms	







- 1. LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



SUPSiC PhotoRelays

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

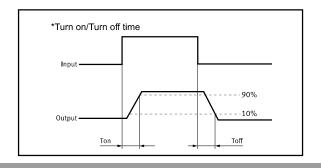
Applications

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoringI/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

	Output rating y Load voltage Load current Package					
Category			Part No.	Packing quantity		
AC/DC	400)/	0.054	DIP-4	GAQY274AE	100pcs/tube	
AC/DC 400V	0.35A	SMD-4	GAQY274AEH	2000pcs/1reel		





Absolute Maximum Ratings (Ta = 25°C)

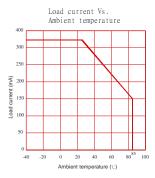
	Item	Symbol	Value	Units	Note
	Continuous LED Current	lF	50	mA	
Input	Peak LED Current	I _{FP}	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	P _{In}	75	mW	
Output	Load Voltage	VL	400	V(AC peak or DC)	
	Load Current	lι	0.35	Α	
	Peak Load Current	Peak	0.8	А	100ms(1 pulse)
	Output Power Dissipation	Pout	300	mW	
Total Powe	er Dissipation	Рт	350	mW	
I/O Isolati	on Voltage	V _{I/O}	5000	Vrms	RH=60%, 1min
Operating	Temperature	Topr	-40 to +85	°C	
Storage Temperature		T _{stg}	-40 to +100	°C	
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.

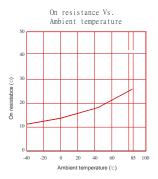
Electrical Specifications (Ambient Temperature: 25°C)

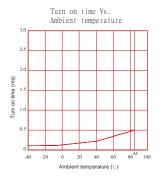
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	V _F		1.2	1.4	V	I⊧=10mA
Input	Operation LED Current	IF on		0.5	3.0	mA	
	Recovery LED Current	IF off		0.35	0.5	mA	
	Recovery LED Voltage	V _F off	0.5			V	
		_					I⊧=5mA,I∟=100mA,
	On-Resistance	Ron		8	12	Ω	Time to flow is within 1 sec.
Output							
	Off-State Leakage		2.24	0.00	0.40		V∟=Rating
	Current	Leak	0.01	0.03	0.10	uA	
	Output Capacitance	Cout		60		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.5	1	ms	I _F =5mA, I _L =100mA,
sion	Turn-Off Time	T _{off}		0.03	0.5	ms	
Coupled	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
Coupled	I/O Capacitance	C _{I/O}		0.8	1.5	pF	f=1MHz

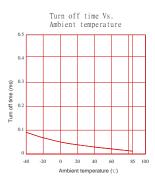
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

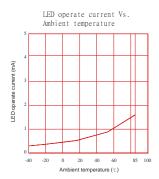
Engineering Data

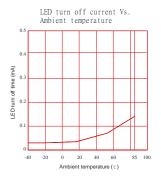


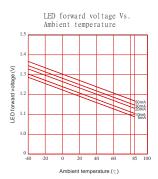


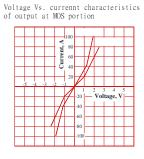


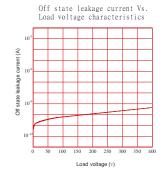


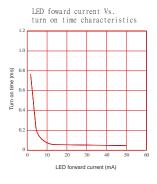


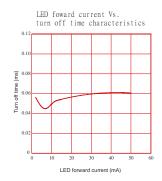


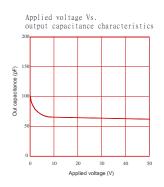




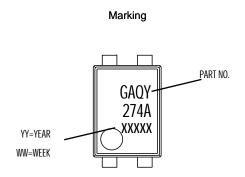


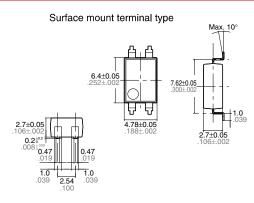






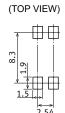
Dimensions and SMD-4 Package Unit: mm





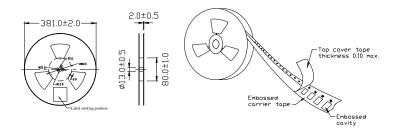
Terminal thickness: t = 0.2 General tolerance: ±0.1

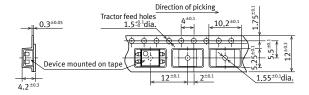
Recommended mounting pad



Tolerance: ±0.1

Tape dimensions (tape reel)



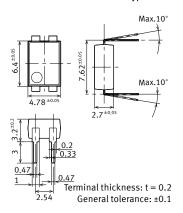


Dimensions and DIP-4 Package

Unit: mm

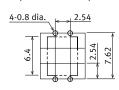
Marking GAQY 274A YY=YEAR WW=WEEK

Surface mount terminal type



PC board pattern

(BOTTOM VIEW)

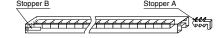


Tolerance: ±0.1

Tape dimensions (tape reel)

DIP type

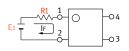
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

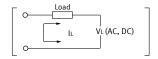




Using Methods

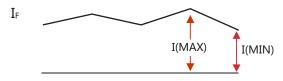
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)			
3.3V	300 Ω			
5.0V	600 Ω			
12V	1.9KΩ			
24V	4.1K Ω			

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

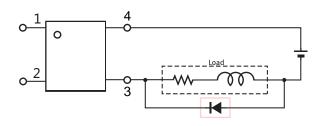
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

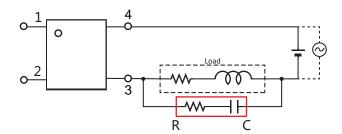
Protection Circuit

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



Recommended Soldering Conditions

(a) Infrared reflow soldering:

■ Peak reflow soldering : 260°C or below (package surface temperature)

■ Time of peak reflow temperature : 10 sec
 ■ Time of temperature higher than 230°C : 30-60 sec
 ■ Time to preheat temperature from 180~190°C : 60-120 sec

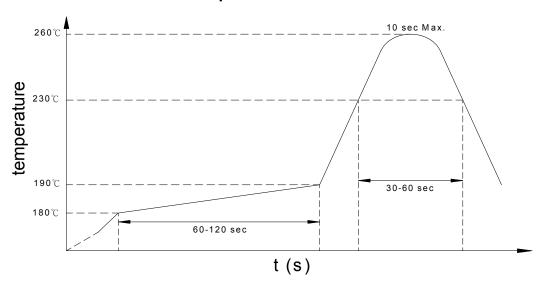
■ Time(s) of reflow: Two

■ Flux: Rosin flux containing small amount of chlorine (The

flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering:

■ Temperature : 260°C or below (molten solder temperature)

■ Time : 10 seconds or less

■ Preheating conditions : 120°C or below (package surface temperature)

■ Time(s) of reflow : One

■ Flux: Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(c) Cautions:

■ Fluxes : Avoid removing the residual flux with freon-based and chlorine-based

cleaning solvent.

Avoid shorting between portion of frame and leads.